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(54) MANUFACTURING METHOD OF ELECTRONIC COMPONENTS

(57)Abstract:

PROBLEM TO BE SOLVED: To find a new bonding method of easy bonding and peeling.

SOLUTION: In this manufacturing method of electronic components, one side (A surface) of a semiconductor substrate is subjected to a circuit component formation process including the introduction of impurities, the side of the surface A is bonded to a retention substrate (BP), an exposure surface (B surface) is subject to rear surface treatment process requiring polishing up to a thickness of 100 μm or less as a thin substrate where electronic components are formed, and the thin substrate is peeled off from the retention substrate (BP). In addition, as the protection film of the circuit components on the A surface, an organic protection film (RC) is used for bonding by the organic protection film, thus achieving peel-off even in the case of peel-off where adhesion force has been increased and peel-off is extremely difficult.

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